MMBV3401LT1G

Silicon Pin Diode

This device is designed primarily for VHF band switching applications but is also suitable for use in general–purpose switching circuits. Supplied in a Surface Mount package.

Features

- Rugged PIN Structure Coupled with Wirebond Construction for Optimum Reliability
- Low Capacitance 0.7 pF (Typ) at $V_R = 20$ Vdc
- Very Low Series Resistance at 100 MHz
 0.34 Ω (Typ) @ I_F = 10 mAdc
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



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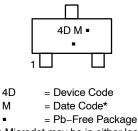
SOT-23 (TO-236AB) CASE 318-08 STYLE 8

MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Reverse Voltage	V _R	35	Vdc	
Forward Power Dissipation @ T _A = 25°C Derate above 25°C	PD	200 2.0	mW mW/°C	
Junction Temperature	TJ	+125	°C	
Storage Temperature Range	T _{stg}	–55 to +150	°C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.





(Note: Microdot may be in either location) *Date Code orientation and/or overbar may vary

depending upon manufacturing location.

ORDERING INFORMATION

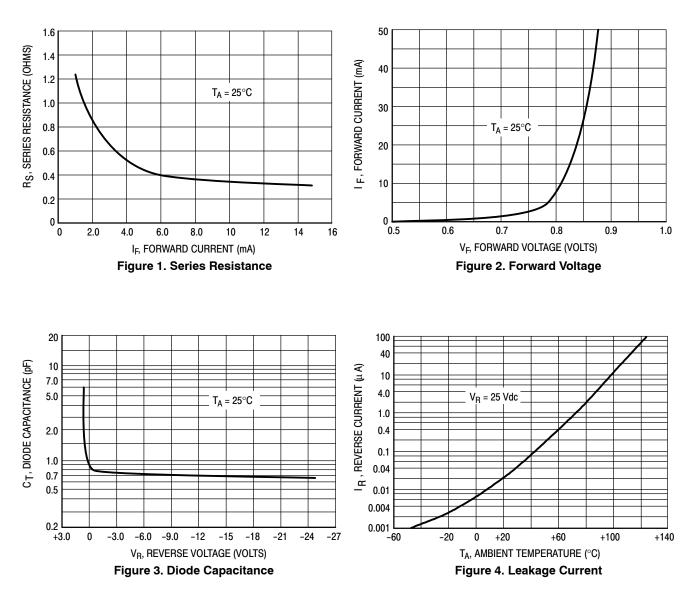
Device	Package	Shipping [†]
MMBV3401LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel
MMBV3401LT3G	SOT-23 (Pb-Free)	10,000 Tape & Reel

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MMBV3401LT1G

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

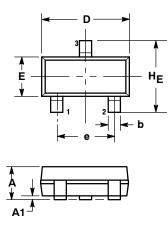
Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μAdc)	V _{(BR)R}	35	-	-	Vdc
Diode Capacitance (V _R = 20 Vdc)	C _T	-	-	1.0	pF
Series Resistance (Figure 1) (I _F = 10 mAdc, f = 100 MHz)	R _S	-	-	0.7	Ω
Reverse Leakage Current (V _R = 25 Vdc)	I _R	-	-	0.1	μAdc

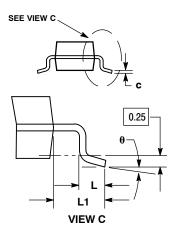


TYPICAL CHARACTERISTICS

PACKAGE DIMENSIONS

SOT-23 (TO-236AB) CASE 318-08 **ISSUE AN**





NOTES:

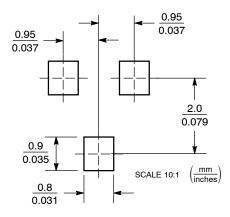
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982 2
- CONTROLLING DIMENSION: INCH. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM З. THICKNESS OF BASE MATERIAL.
- 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08 4.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
Е	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 8:

- PIN 1. ANODE 2. NO CONNECTION
 - З. CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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